Development of Embedded Systems for Continuous Monitoring of Additively-Manufactured Flexible Sensors and Reliability Modeling of Large-Scale Flip-Chip Ball Grid Arrays

by

Brett Cranston

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Approved by

Pradeep Lall, Chair, MacFarlane Endowed Distinguished Professor of Mechanical Engineering Chad Rose, Assistant Professor of Mechanical Engineering Robert Dean, McWane Professor of Electrical and Computer Engineering This thesis has been redacted.